

**General Description**

This planar stripe MOSFET has better characteristics, such as fast switching time, low on resistance, low gate charge and excellent avalanche characteristics. It is mainly suitable for active power factor correction and switching mode power supplies.

**FEATURES**

- $V_{DSS}=500V$ ,  $I_D=10A$
- Drain-Source ON Resistance :  
 $R_{DS(ON)}(\text{Max})=0.65 \Omega$  @  $V_{GS}=10V$
- $Q_g(\text{typ.})=19.5nC$

**MAXIMUM RATING (Tc=25 °C)**

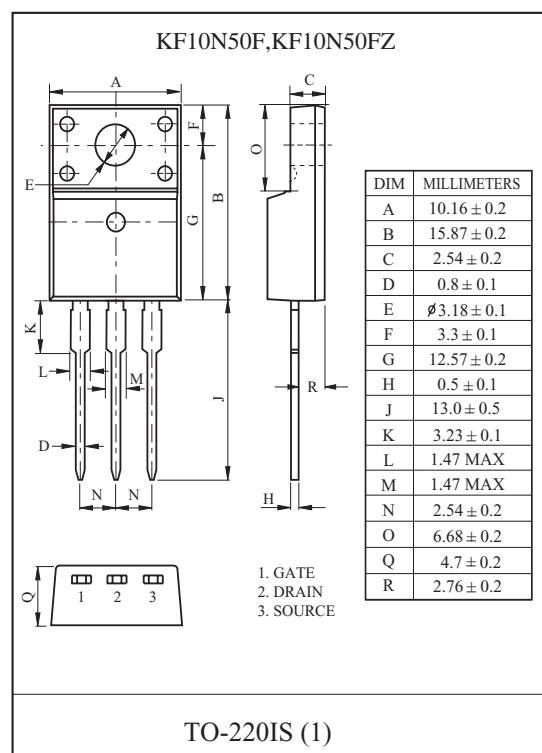
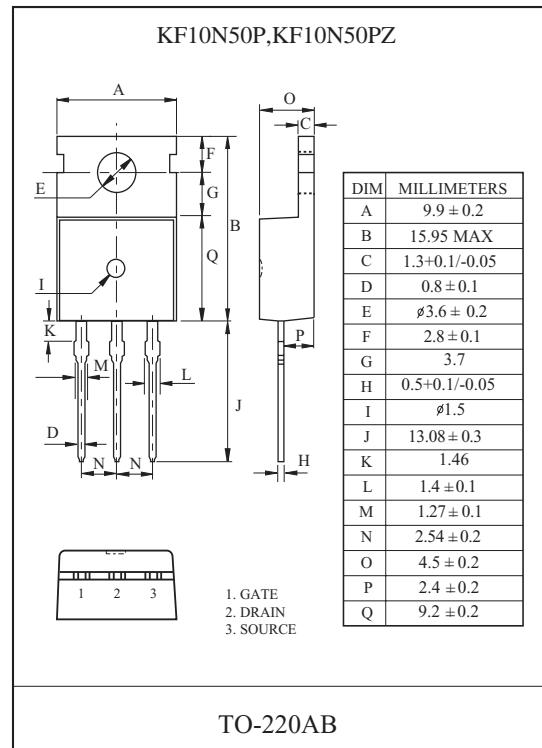
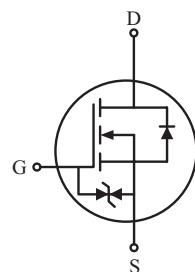
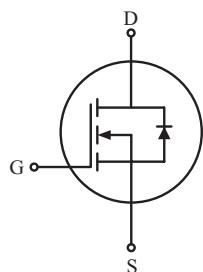
CHARACTERISTIC	SYMBOL	RATING		UNIT
		KF10N50P KF10N50PZ	KF10N50F KF10N50FZ	
Drain-Source Voltage	$V_{DSS}$	500		V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$		V
Drain Current	$I_D$ @ $T_C=25^\circ\text{C}$	10	10*	A
	$I_D$ @ $T_C=100^\circ\text{C}$	5	5*	
	$I_{DP}$ Pulsed (Note1)	25	25*	
Single Pulsed Avalanche Energy (Note 2)	$E_{AS}$	300		mJ
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	14.7		mJ
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns
Drain Power Dissipation	$P_D$ Tc=25 °C	130	41.5	W
	$P_D$ Derate above 25 °C	1.04	0.33	W/°C
Maximum Junction Temperature	$T_j$	150		°C
Storage Temperature Range	$T_{stg}$	-55 ~ 150		°C
<b>Thermal Characteristics</b>				
Thermal Resistance, Junction-to-Case	$R_{thJC}$	0.96	3.0	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	62.5	°C/W

\* : Drain current limited by maximum junction temperature.

**PIN CONNECTION**

(KF10N50P, KF10N50F)

(KF10N50PZ, KF10N50FZ)



# KF10N50P/F/PZ/FZ

## ELECTRICAL CHARACTERISTICS (Tc=25 °C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V	500	-	-	V
Breakdown Voltage Temperature Coefficient	ΔBV <sub>DSS</sub> /ΔT <sub>j</sub>	I <sub>D</sub> =250 μA, Referenced to 25 °C	-	0.6	-	V/°C
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	-	-	10	μA
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	2	-	4	V
Gate Leakage Current	I <sub>GSS</sub>	KF10N50P/F	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100 nA
		KF10N50PZ/FZ	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V	-	-	±10 μA
Drain-Source ON Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	-	0.54	0.65	Ω
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =10A V <sub>GS</sub> =10V (Note4,5)	-	19.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.5	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	8.7	-	
Turn-on Delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =250V I <sub>D</sub> =10A R <sub>G</sub> =25 Ω (Note4,5)	-	27	-	ns
Turn-on Rise time	t <sub>r</sub>		-	35	-	
Turn-off Delay time	t <sub>d(off)</sub>		-	60	-	
Turn-off Fall time	t <sub>f</sub>		-	29	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	880	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	12	-	
Output Capacitance	C <sub>oss</sub>		-	133	-	
<b>Source-Drain Diode Ratings</b>						
Continuous Source Current	I <sub>S</sub>	V <sub>GS</sub> <V <sub>th</sub>	-	-	10	A
Pulsed Source Current	I <sub>SP</sub>		-	-	40	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V	-	-	1.4	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V, dI <sub>s</sub> /dt=100A/μs	-	320	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	3.5	-	μC

Note 1) Repetitivity rating : Pulse width limited by junction temperature.

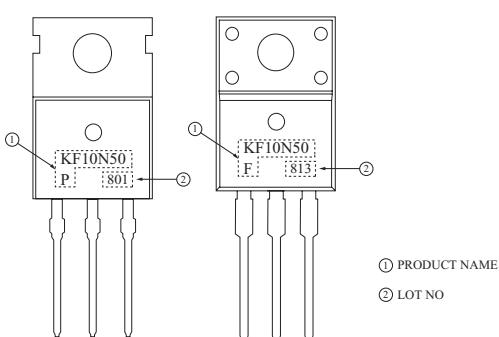
Note 2) L =5.5mH, I<sub>S</sub>=10A, V<sub>DD</sub>=50V, R<sub>G</sub>=25 Ω, Starting T<sub>j</sub>=25 °C.

Note 3) I<sub>S</sub>≤10A, dI/dt≤200A/μs, V<sub>DD</sub>≤BV<sub>DSS</sub>, Starting T<sub>j</sub>=25 °C.

Note 4) Pulse Test : Pulse width ≤ 300μs, Duty Cycle ≤ 2%.

Note 5) Essentially independent of operating temperature.

## Marking



# KF10N50P/F/PZ/FZ

Fig1.  $I_D$  -  $V_{DS}$

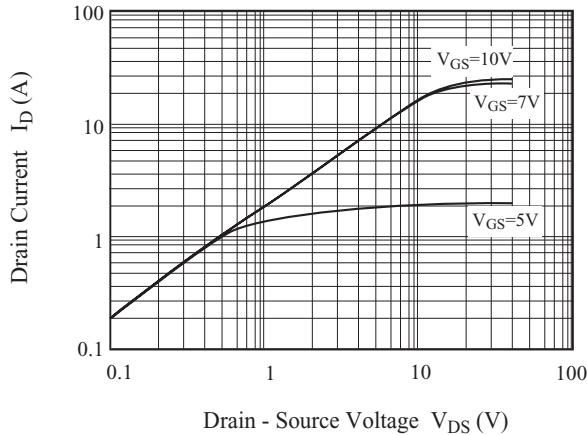


Fig2.  $I_D$  -  $V_{GS}$

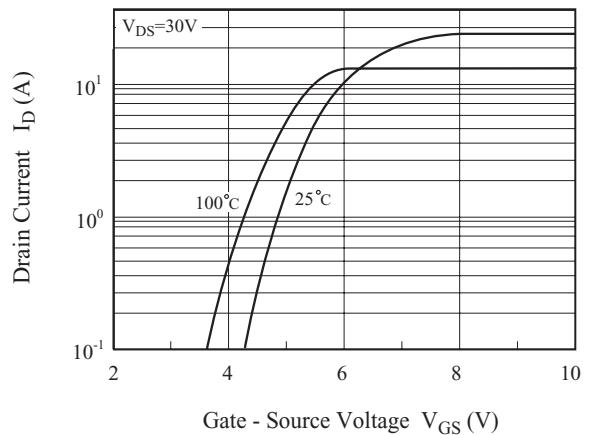


Fig3.  $BV_{DSS}$  -  $T_j$

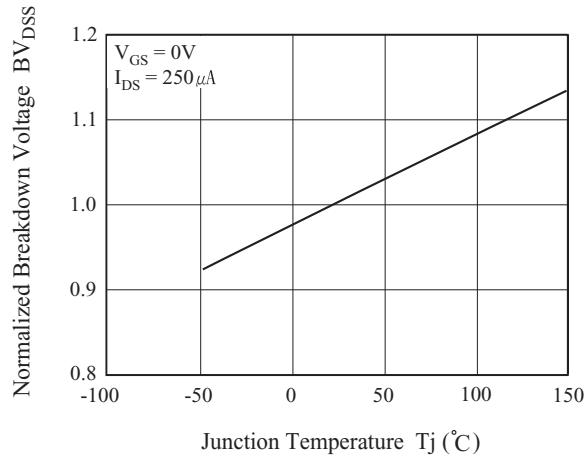


Fig4.  $R_{DS(ON)}$  -  $I_D$

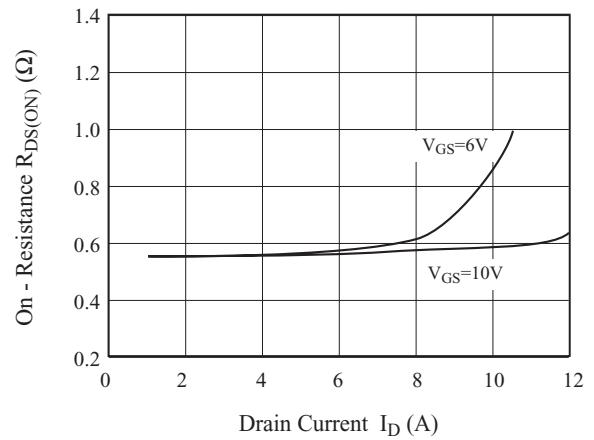


Fig5.  $I_S$  -  $V_{SD}$

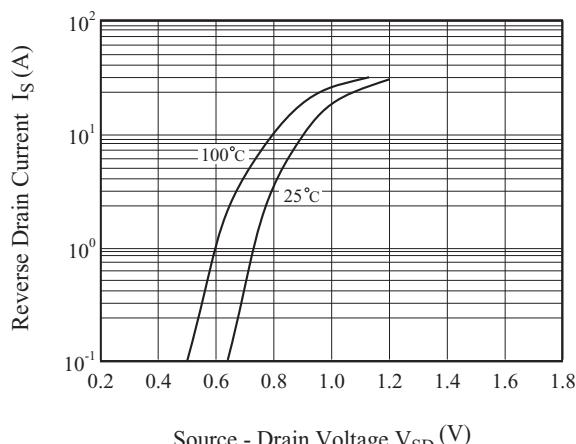
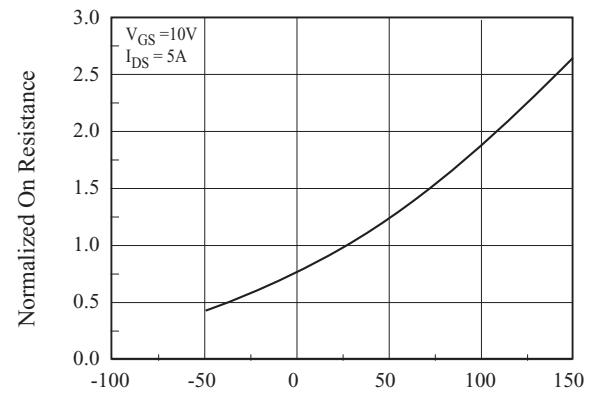


Fig6.  $R_{DS(ON)}$  -  $T_j$



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Fig 7. C - V<sub>DS</sub>

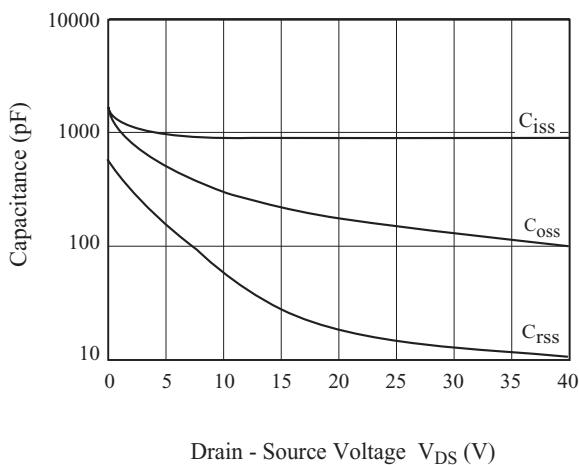


Fig8. Q<sub>g</sub>- V<sub>GS</sub>

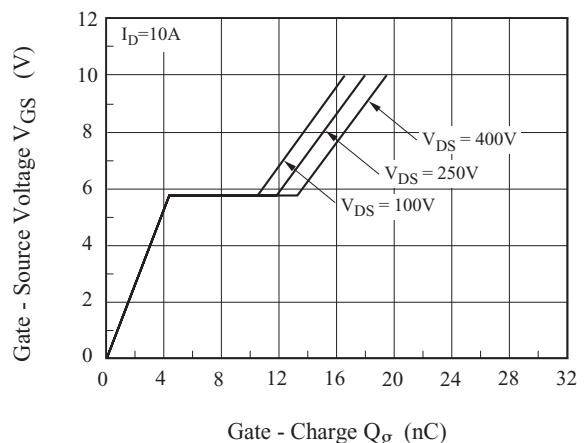


Fig9. Safe Operation Area

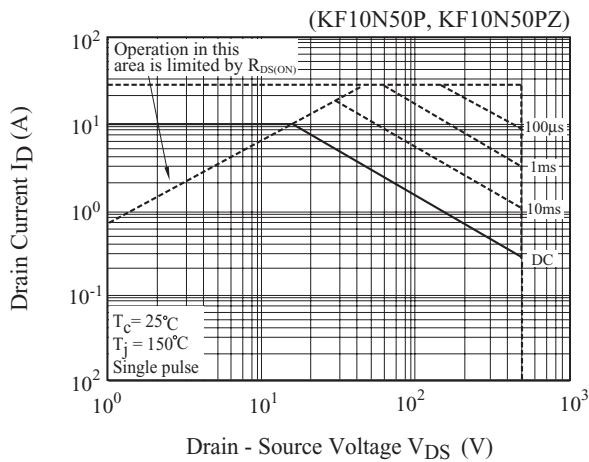


Fig10. Safe Operation Area

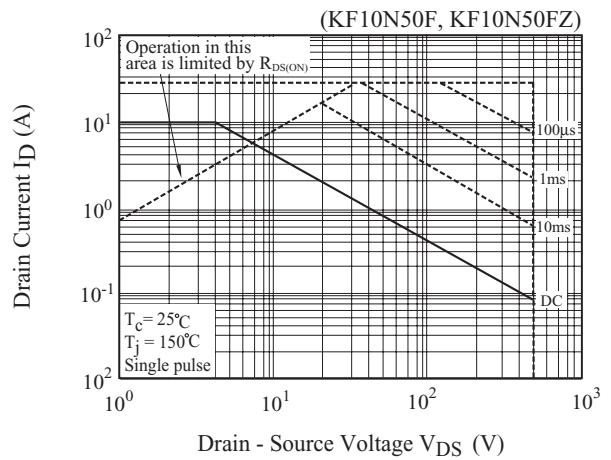
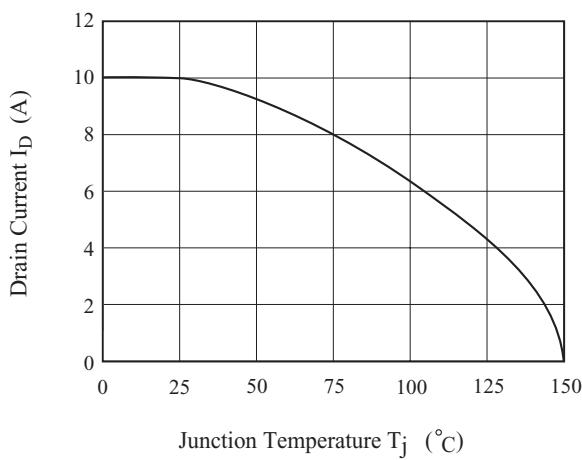


Fig11. I<sub>D</sub> - T<sub>j</sub>



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Fig12. Transient Thermal Response Curve

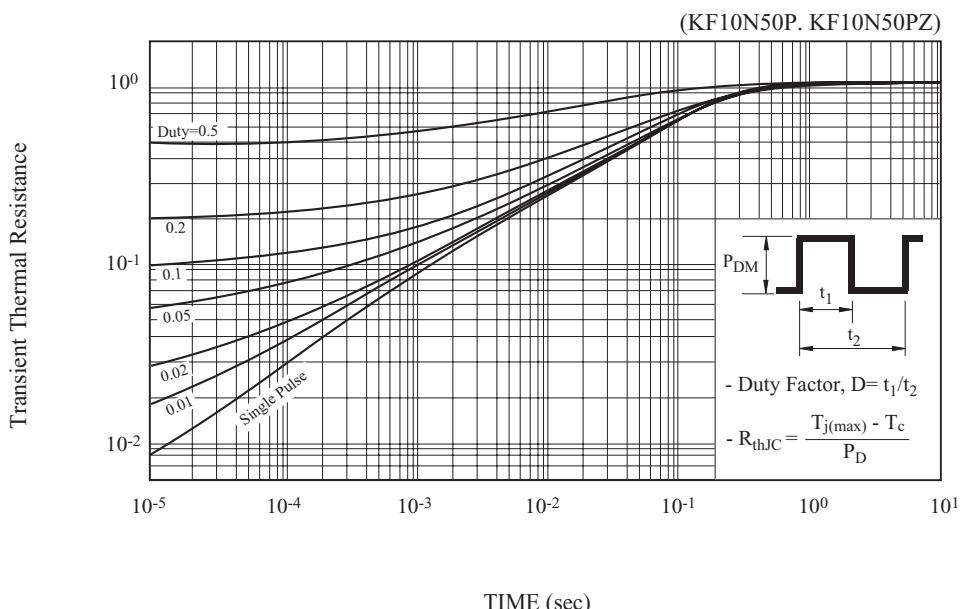
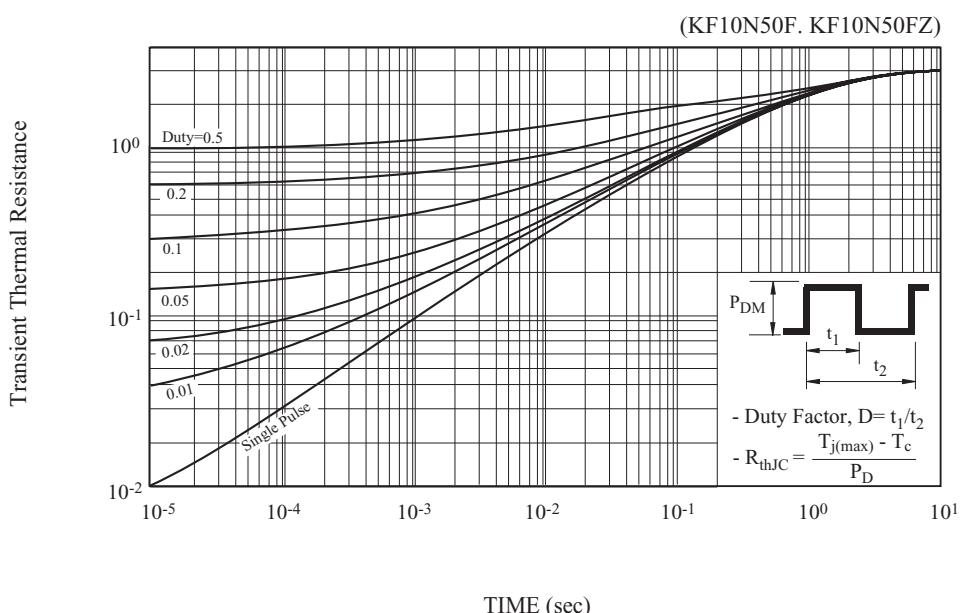


Fig13. Transient Thermal Response Curve



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Fig14. Gate Charge

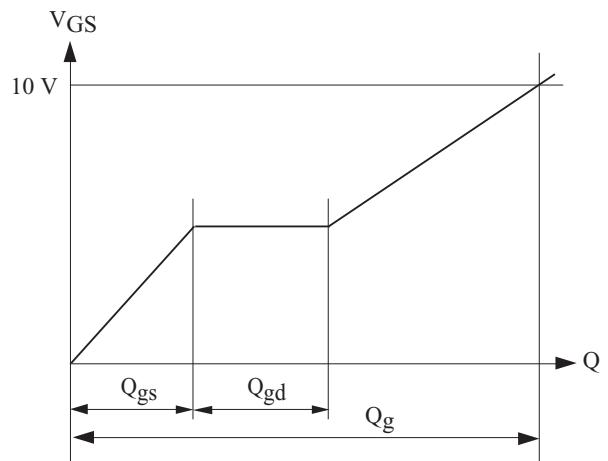
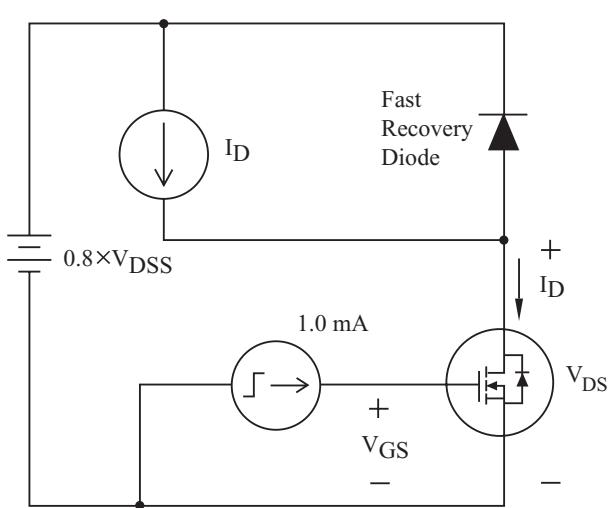
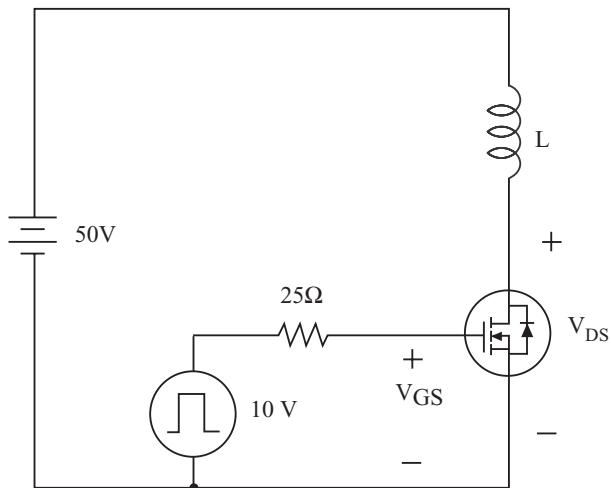


Fig15. Single Pulsed Avalanche Energy



$$E_{AS} = \frac{1}{2} L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

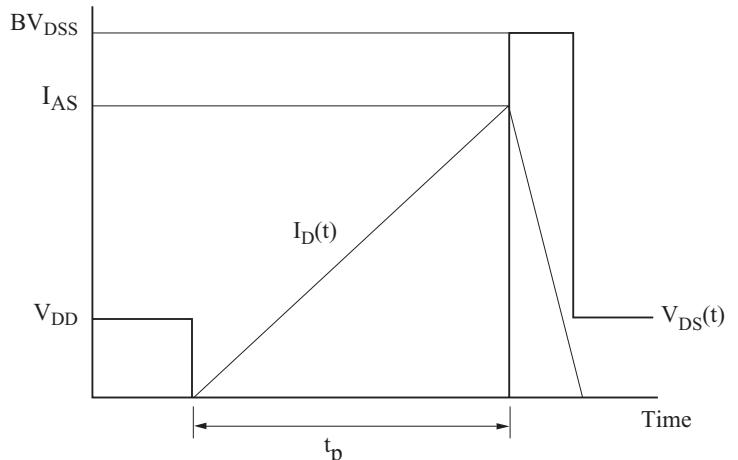
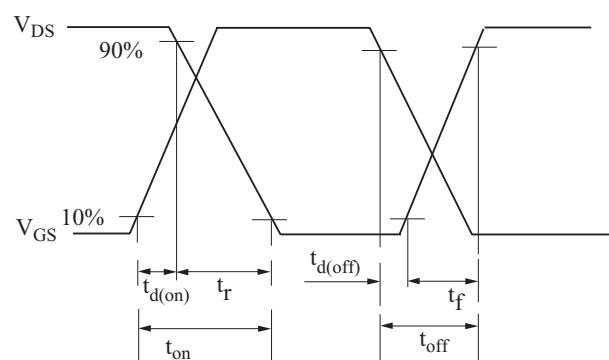
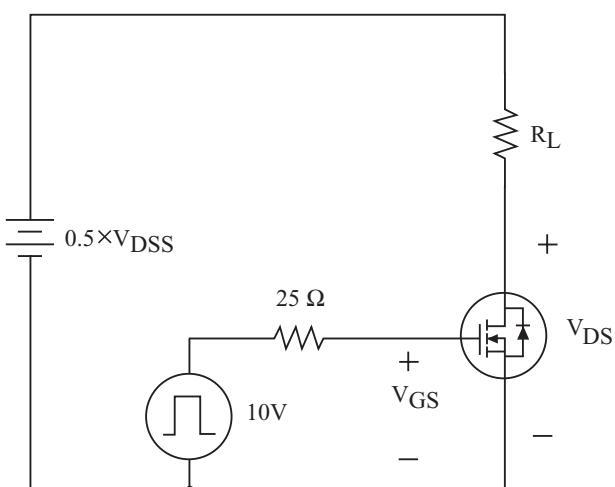


Fig16. Resistive Load Switching



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Fig17. Source - Drain Diode Reverse Recovery and dv /dt

